



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hembree et al.

Serial No.: 10/651,664

Filed: August 29, 2003

For: METHOD AND PROCESS OF
CONTACT TO HEAT SOFTENED
SOLDER BALL ARRAY

Confirmation No.: 9327

Examiner: J. Jeffery

Group Art Unit: 3742

Attorney Docket No.: 2269-3634.4US
(97-1094.04/US)

Notice of Allowance Mailed:

June 3, 2005

NOTICE OF EXPRESS MAILING

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Serial No. 10/651,664

Amendments to the Claims are reflected in the listing of claims which begins on page 9 of this paper.

Remarks begin on page 13 of this paper.